

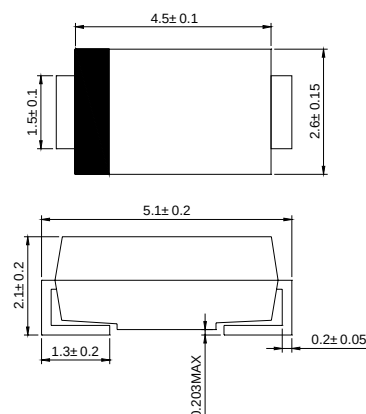
FEATURES

- ◇ Plastic package has underwriters laborator flammability classification 94V-0
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ High temperature soldering:
250°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC DO-214AC, molded plastic over passivated chip
- ◇ Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- ◇ Polarity: color band denotes cathode end
- ◇ Weight: 0.002 ounces, 0.064 gram

DO - 214AC(SMA)



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		RS1A	RS1B	RS1D	RS1G	RS1J	RS1K	RS1M	UNITS
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RWS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ T _L =90°C	I _{F(AV)}	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I _{FSM}	30.0							A
Maximum instantaneous forward voltage at 1.0A	V _F	1.30							V
Maximum DC reverse current @T _A =25°C at rated DC blocking voltage @T _A =125°C	I _R	5.0 50.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C _J	10					7.0		pF
Typical thermal resistance (NOTE 3)	R _{θJA}	105							°C/W
	R _{θJL}	32							
Operating junction and storage temperature range	T _J T _{STG}	- 55 ----- + 150							°C

NOTE: 1. Reverse recovery time test conditions: $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$

2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.2"X0.2" (5.0X5.0mm²) copper pad areas

Fig. 1 — Forward Current Derating Curve

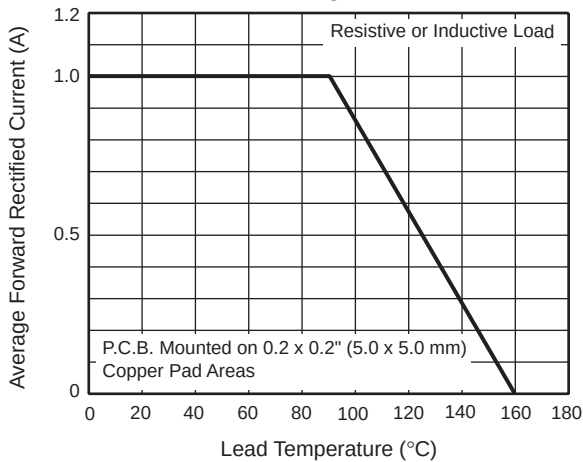


Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current

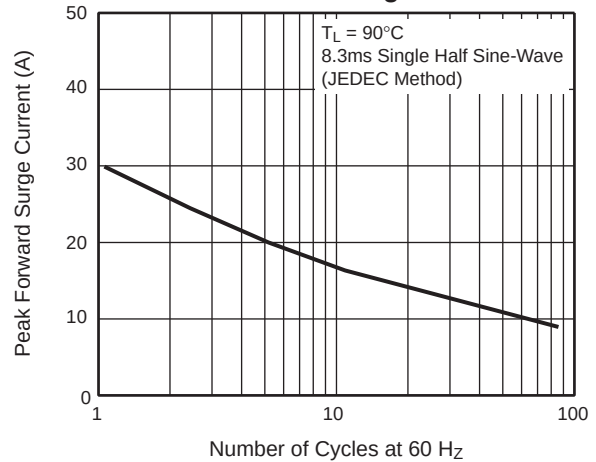


Fig. 3 — Typical Instantaneous Forward Characteristics

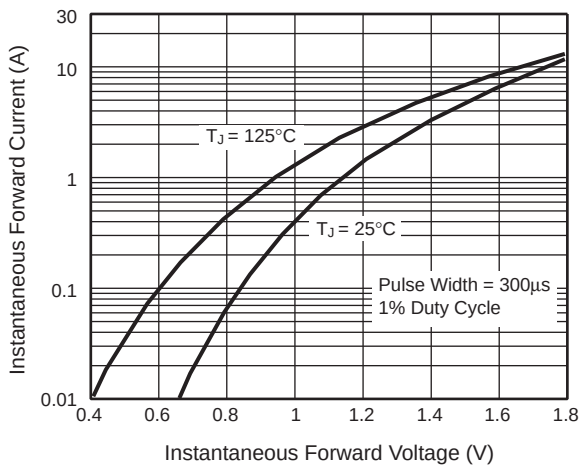


Fig. 4 — Typical Reverse Characteristics

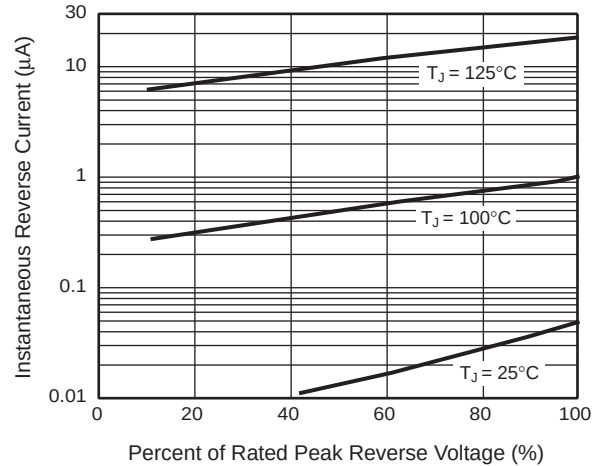


Fig. 5 — Typical Junction Capacitance

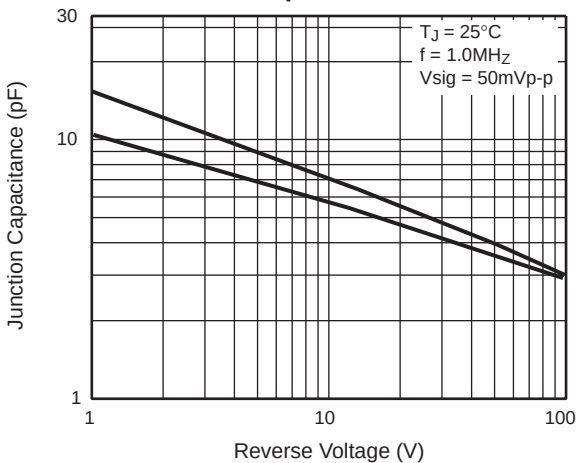


Fig. 6 — Typical Transient Thermal Impedance

